Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
		2.	Min.	Тур.	201/2
APA2106QBC/D	Blue (InGaN)	Water Clear	40	80	120°

Notes:

- 1.01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value. 2.Luminous intensity/ luminous Flux: +/-15%.
- 3.Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Blue	460		nm	IF=20mA
λD [1]	Dominant Wavelength	Blue	465		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Blue	25		nm	IF=20mA
С	Capacitance	Blue	100		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Blue	3.3	4	V	IF=20mA
lr	Reverse Current	Blue		50	uA	VR=5V

Notes:

- 1.Wavelength: +/-1nm. 2.Forward Voltage: +/-0.1V.
- 3.Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

 4.Excess driving current and/or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

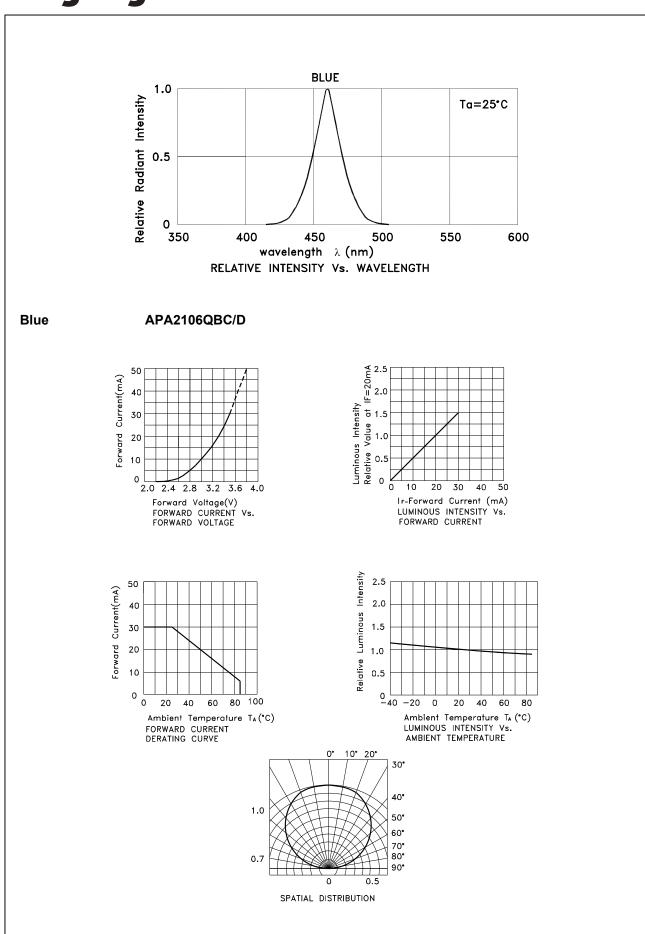
Absolute Maximum Ratings at TA=25°C

Parameter	Blue	Units	
Power dissipation	120	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	150	mA	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

Note:

1.1/10 Duty Cycle, 0.1ms Pulse Width.

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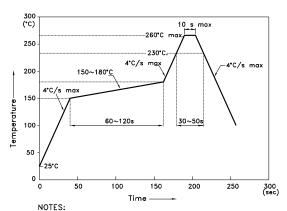
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Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



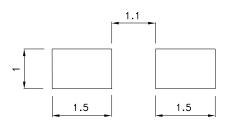
- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

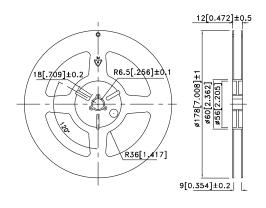
 3.Number of reflow process shall be 2 times or less.

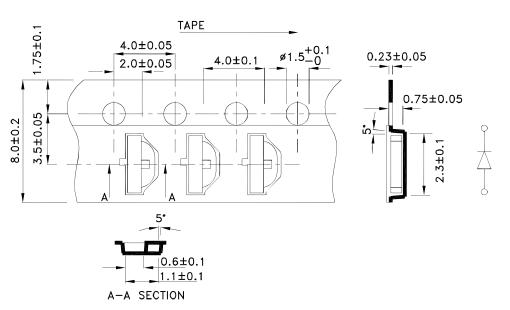
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



Tape Dimensions (Units: mm)

Reel Dimension





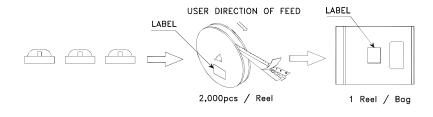
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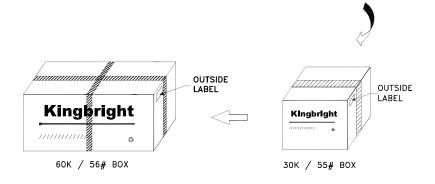
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PACKING & LABEL SPECIFICATIONS

APA2106QBC/D







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